

ABSTRACT OF THE DISCLOSURE

A semiconductor device assembly has a lead frame and a semiconductor die configured to be attached to each other. An adhesive is applied at room temperature through a stencil to the lead frame. The semiconductor die is urged against the adhesive to effect the attachment between the semiconductor device and the lead frame. The adhesive preferably is from about 75 percent to about 95 percent isobutyl acetal diphenol copolymer and from about 25 percent to about 5 percent, respectively, of titanium oxide.

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